

RELIABILITY MONITOR

PRODUCT	MONITOR DATE	DATE CODE	ASSEMBLY FACILITY	ASSEMBLY LOT NO	PROCESS TYPE	PACKAGE TYPE
DS1210	Jan-97	9644 C1	ANAM, K.	DN633466AAB	3.0μ OX/NI	16 SOIC

STRESS/JOB NO.

**READPOINT
(Sample Size/No. of Fails)**

Preconditioning (P/C):
HTC Vapor Phase
P-18967

<u>Electrical</u>	<u>Cum %</u>
233/0	0.0%

Sonoscan
P-19002

<u>Post Vapor Phase</u>
4/0

Infant / High Voltage Life
125°C, 7.0 V.
P-19003, P-19119

<u>48 Hr</u>	<u>336 Hr</u>	<u>1KHr</u>	<u>*Failure Rate</u>
229/0	77/0	77/0	30 Fits

*Chi Squared Method, 60% C. L., 55°C & 5.5V; Temperature Derating: Ea = 0.7 ev; Voltage Derating B = 1.0

Temp Cycle
-55°C to +125°C
P-19120

<u>300 ~</u>	<u>1K ~</u>	<u>Cum %</u>
39/0	39/0	0.0%

Biased Moisture
85°C/85% RH, 5.5 V.
P-19121

<u>274 Hr</u>	<u>959 Hr</u>	<u>Cum %</u>
75/0		

Autoclave
121°C/100% RH, 2 Atmos
P-19122

<u>96 Hr</u>	<u>Cum %</u>
38/0	0.0%

Failure Mode

Failure Analysis